

L*Number	Hits	Search Text	DB	Time stamp
5	2	((injection pressure) and (molding mold) and (device apparatus machine) and (control controls)and (subtractor subtractor)and (clamp clamping)).clm.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/27 13:45
6	1	((injection pressure) and (molding mold) and (device apparatus machine) and (control controls)and (subtractor subtractor)and (clamp clamping)and sensor).clm.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/27 13:45
-	164	73/856.ccls.	USPAT	2001/02/26 09:32
-	10	73/856.ccls. and mold	USPAT	2001/02/26 09:38
-	5	73/856.ccls. and (mold molding) and (injection inject pressure)	USPAT	2001/02/26 09:36
-	40553	(injection pressure) and (molding mold) and (device apparatus machine).clm.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/26 09:42
-	9162	(injection pressure) and (molding mold) and (device apparatus machine) and (control controls).clm.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/26 15:12
-	21	((injection pressure) and (molding mold) and (device apparatus machine) and (control controls) and sensor and switch).clm.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/26 09:57
-	4	((injection pressure) and (molding mold) and (device apparatus machine) and (control controls) and (force pressure strain) near4 sensor and switch).clm.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/26 10:00
-	10	(injection pressure) and (molding mold) and (device apparatus machine) and (control controls)and (subtractor subtractor).clm.	USPAT; EPO; JPO; Derwent; IBM TDB	2001/02/27 13:41